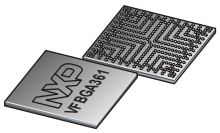
SOT2306-1

VFBGA361, very thin fine-pitch ball grid array, 361 terminals, 0.5 mm pitch, 13 mm x 13 mm x 0.86 mm body

15 October 2026 Package information

1 Package summary



Terminal position code	B (bottom)
Package type descriptive code	VFBGA361
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-10-2026
Manufacturer package code	98ASA02298D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	12.85	13	13.15	mm
package width	12.85	13	13.15	mm
seated height	-	0.86	0.98	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	361	-	

VFBGA361, very thin fine-pitch ball grid array, 361 terminals, 0.5 mm pitch, 13 mm x 13 mm x 0.86 mm body

2 Package outline

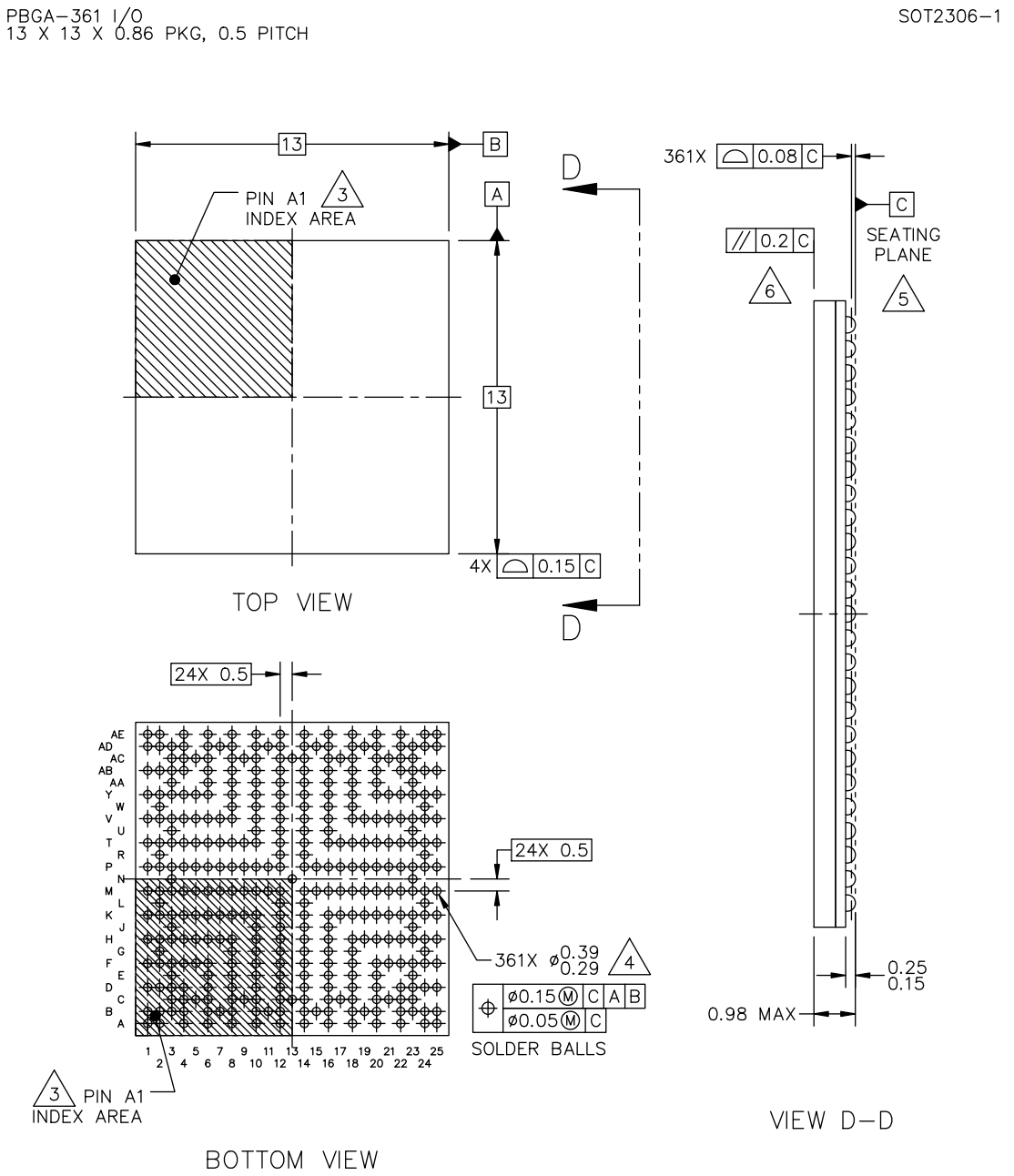


Figure 1. Package outline VFBGA361 (SOT2306-1)

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3 Soldering

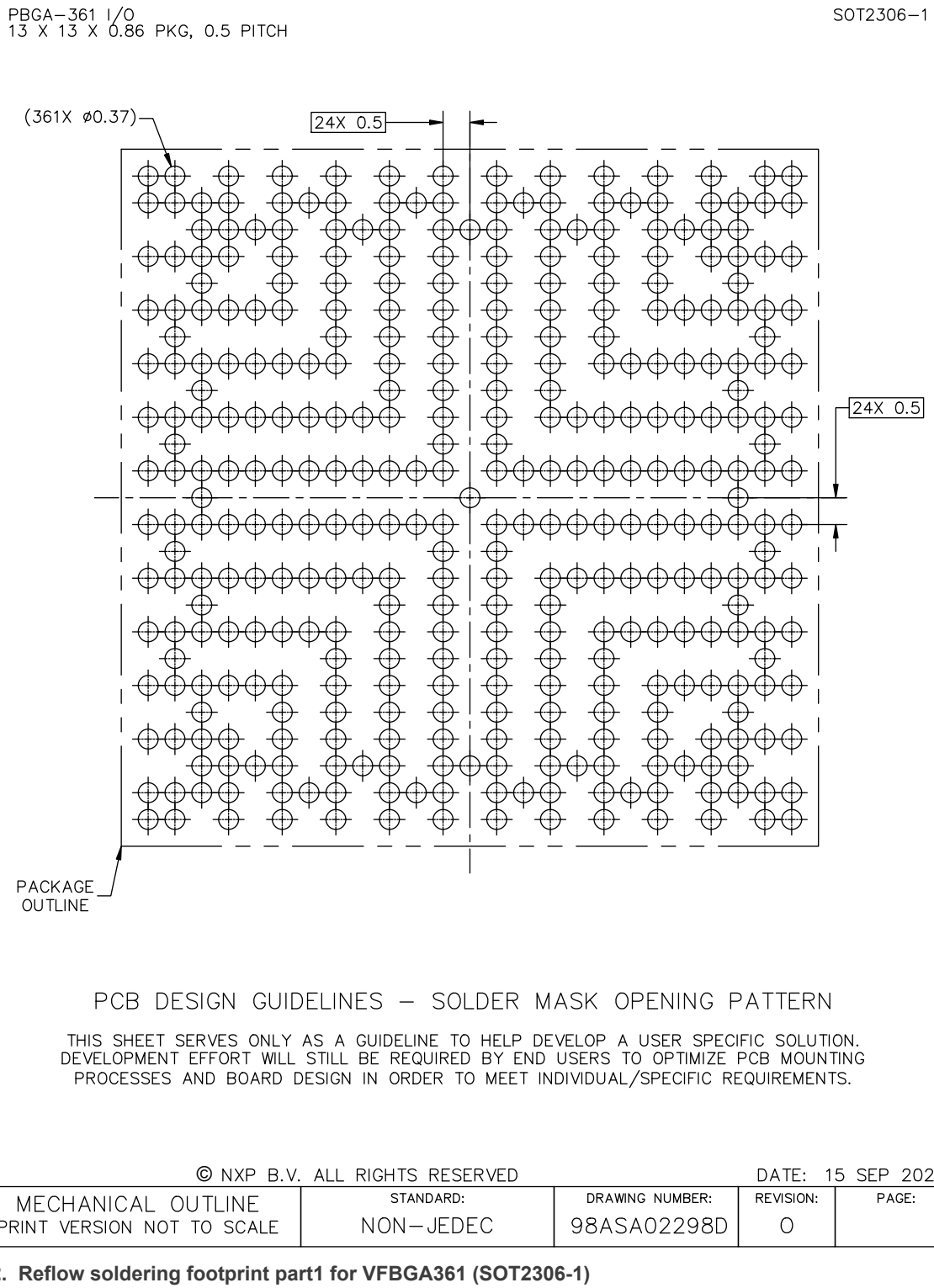


Figure 2. Reflow soldering footprint part1 for VFBGA361 (SOT2306-1)

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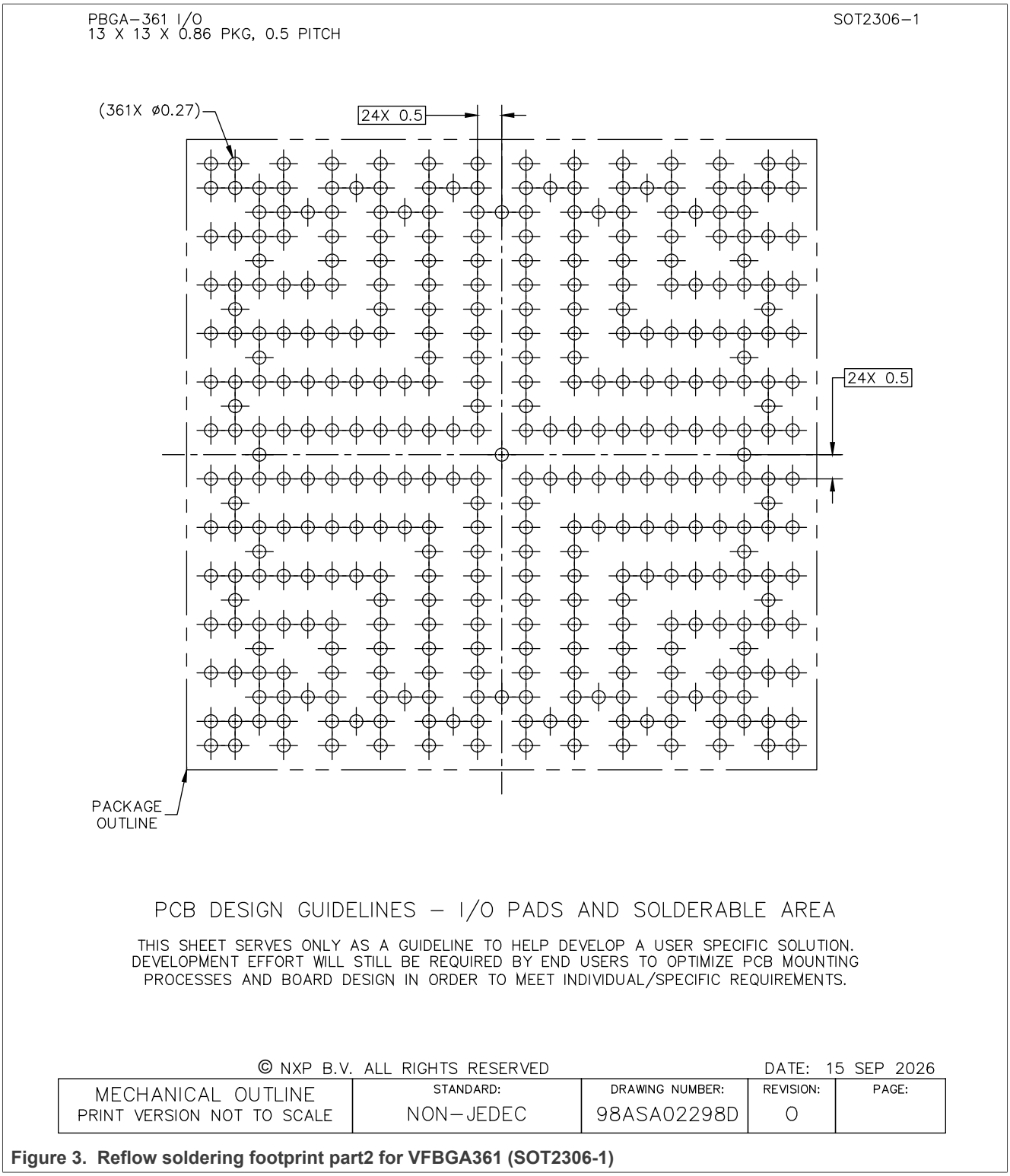


Figure 3. Reflow soldering footprint part2 for VFBGA361 (SOT2306-1)

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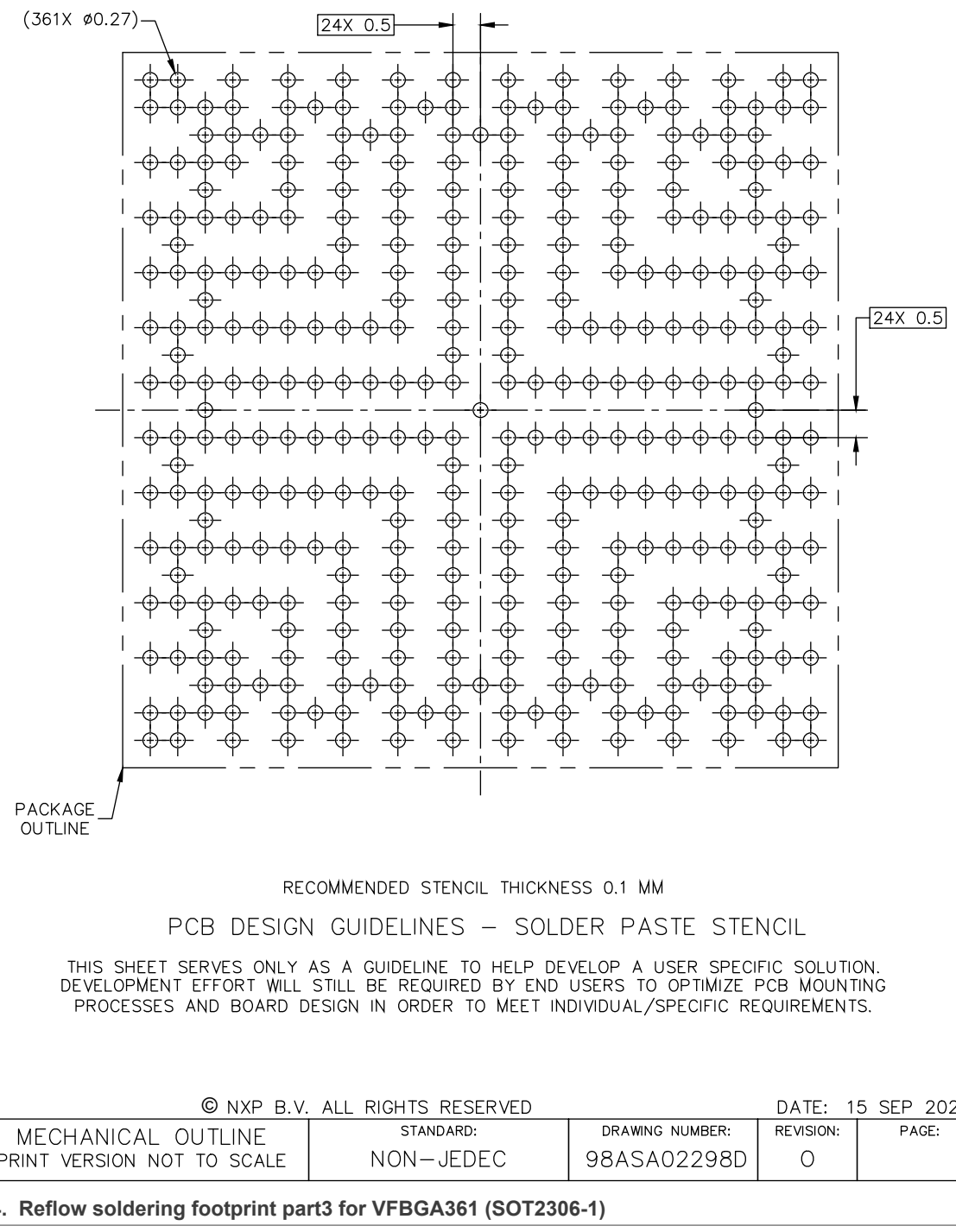


Figure 4. Reflow soldering footprint part3 for VFBGA361 (SOT2306-1)

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VFBGA361, very thin fine-pitch ball grid array, 361 terminals, 0.5 mm pitch, 13 mm x 13 mm x 0.86 mm body

PBGA−361 I/O
13 X 13 X 0.86 PKG, 0.5 PITCH

SOT2306−1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 15 SEP 2026

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON−JEDEC	DRAWING NUMBER: 98ASA02298D	REVISION: O	PAGE:

Figure 5. Package outline note VFBGA361 (SOT2306-1)

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SOT2306-1

VFBGA361, very thin fine-pitch ball grid array, 361 terminals, 0.5 mm pitch, 13 mm x 13 mm x 0.86 mm body

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3 Soldering 3
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